



IFUG

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR
PACKAGE DEVICE WITH BENT AND FLAT LEADS
Serial No.: 10/695,564 Filed: October 28, 2003
Examiner: Williams, A. Group Art Unit: 2826
Atty. Docket No.: BDG005-6

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

In response to the Office Action dated June 22, 2004, please amend the application as follows.

The Claim Amendments begin at page 2.

The Remarks begin at page 25.